

CLAIMS

1. A process for manufacturing a wiring board,  
said process comprising the following steps of:

5 making a resin plate having wiring pattern  
recesses and via through holes;

coating all of the surfaces of the resin  
plate including inner walls of said wiring pattern  
recesses and via through holes with a metal film;

10 applying an electro-plating using said  
metal film as a power-supply layer to fill a plated metal  
into said wiring pattern recesses and via through holes;  
and

15 removing said metal film formed on said  
resin plate except for the inner walls of said wiring  
pattern recesses and via through holes, so that wiring  
pattern and vias are exposed on a surface the same as  
that of said resin plate.

2. A process as set forth in claim 1, wherein said  
resin plate is formed by press-forming process.

20 3. A process as set forth in claim 1, wherein said  
resin plate is formed by an injection molding process.

4. A process as set forth in claim 1 further  
comprising the following steps of:

25 forming pads on one surface of the wiring  
board to which external connecting terminals are to be  
attached.

5. A process as set forth in claim 1 further  
comprising the following steps of:

30 using said wiring board as a core  
substrate; and

forming wiring patterns on the respective  
surface of the core substrate by means of resin layers to  
obtain a multi-layer wiring board.

35 6. A process for manufacturing a multi-layer  
wiring board, said process comprising:  
(a) manufacturing a core substrate comprising  
the steps of:

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making a resin plate having wiring pattern recesses and via through holes;

coating all of the surfaces of the resin plate including inner walls of said wiring pattern recesses and via through holes with a metal film;

5 applying an electro-plating using said metal film as a power-supply layer to fill a plated metal into said wiring pattern recesses and via through holes; and

10 removing said metal film formed on said resin plate except for the inner walls of said wiring pattern recesses and via through holes, so that wiring pattern and vias are exposed on a surface the same as that of said resin plate; and

15 (b) forming resin layers on respective surfaces of said core substrate so that said resin layers includes wiring pattern recesses and via through holes;

(c) coating all of surfaces of said resin layers including inner walls of said wiring pattern recesses and via through holes with a metal film;

20 (d) applying an electro-plating using said metal film as a power-supply layer to fill a plated metal into said wiring pattern recesses and via through holes; and

25 (e) removing said metal film attached to said resin layer except for the inner walls of said wiring pattern recesses and via through holes, so that wiring pattern and vias are exposed on a surface same as that of said resin plate.

30 7. A process as set forth in claim 6, wherein said resin layer is formed by a press-forming process.

8. A process as set forth in claim 6, wherein said resin plate is formed by a injection molding process.